

## Market News

### **CoolMOS™ C7 650 V Gold with TO-Leadless package delivers high performance with a small footprint**

Munich, Germany – May 12, 2016 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) launched a new device of the CoolMOS™ family: the CoolMOS C7 Gold 650 V in a TO-Leadless package. This combination of improved superjunction (SJ) semiconductor process and advanced SMD package design is delivering unparalleled performance in hard switching applications. The small footprint of this package brings power density advantages for server, telecom and solar applications.

The C7 Gold CoolMOS technology comes with 4pin Kelvin Source capability and improved thermal properties of the TO-Leadless package. This enables a viable SMD solution for high current topologies such as Power Factor Correction (PFC) up to 3 kW. The increased C7 Gold performance leads to higher efficiency which is generating less switching losses and thereby less thermal losses. The C7 Gold technology has the world's lowest  $R_{on} \cdot A$  and a small dimensions with only 115 mm<sup>2</sup>. This also brings power density with the lowest  $R_{DS(on)}$  of 33 mΩ achievable in such a small footprint.

#### **Gold without Lead**

Compared to other traditional SMD packages such as D<sup>2</sup>PAK, the TO-Leadless package has a reduction of 30 percent for footprint, 50 percent for height and 60 percent for space. The package can also be connected either as a standard 3pin MOSFET or using the 4pin Kelvin Source concept. The implementation of this feature brings additional benefits in efficiency particularly at full load, and makes it easier to use by also reducing ringing on the gate.

The high quality TO-Leadless package has a very low source inductance of 1 nH, is lead-free and MSL1 compliant. It features easy visual solder inspection and is suitable for wave and reflow soldering. Compared to a Through Hole package, the TO-Leadless has more to it than higher power density. It can also help in realizing cost savings in manufacturing due to the simple mounting process of SMD packages.

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### **Availability**

The CoolMOS C7 650 V Gold TO-Leadless can be ordered now. Further information is available at [www.infineon.com/c7-gold-toll](http://www.infineon.com/c7-gold-toll).

### **Infineon at the PCIM 2016**

At PCIM 2016 tradeshow, Infineon is presenting leading edge technology for efficient systems in industrial, consumer and automotive applications at booth #412 in hall 9 (Nuremberg, Germany, May 10-12, 2016). An overview of Infineon's PCIM show highlights is available at [www.infineon.com/pcim](http://www.infineon.com/pcim).

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